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(54) IC CARD

(57) Abstract:

PURPOSE: To obtain a thin, non-contact type IC card superior in smoothness on a card surface, adhesive loading properties on a conductive ink printing circuit, workability, and profitability by a method wherein a loading thickness of an adhesive laminated on a printing circuit layer is determined to be a specific multiple of the thickness of the conductive ink printing circuit.

CONSTITUTION: A non-contact type IC card is obtained by laminating in a contact state under heat and pressure a skin layer formed by applying an adhesive 2 to one surface of a polyester film 1, a spacer layer formed by applying an adhesive 4 to one surface of a polyester film 3 and, thereafter, perforating only a part corresponding to an IC chip 6, and a printing circuit layer formed by printing an antenna part 8 and a circuit part 9 using a silver paste on a polyester film 7 and connecting the IC chip 6 onto the circuit part 9. At this time, the loading thickness of the adhesive 4 to be laminated on the printing circuit layer is determined to be 1-1.5 times larger than the thickness of the printing circuit of the conductive ink. In this manner, the IC card has a thickness smaller than a standard thickness of a magnetic card. Nonexistence of residual bubbles between inner circuits improves a reliability in heat resistance and the like.